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# PROBE TIP DESIGN APPLIED IN A FLIP CHIP PACKAGING PROCESS

## Abstract

The present invention provides a novel probe tip suited for flip-chip packaging process. The probe tip comprises a needle body; and a stop cylinder having a recess for fittingly accommodating the needle body therein, the needle body being electrically connected to the stop cylinder via a resilient conductive material. The stop cylinder has an annual flat bottom surrounding the needle body for pressing a protruding probe mark on a metal pad scratched by the needle body.